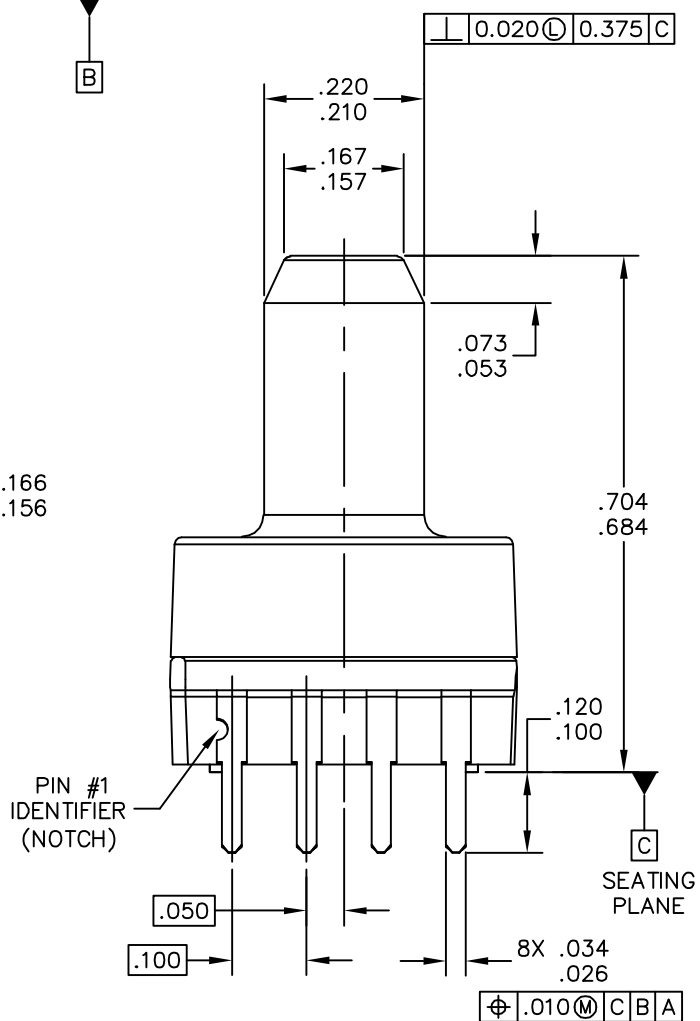
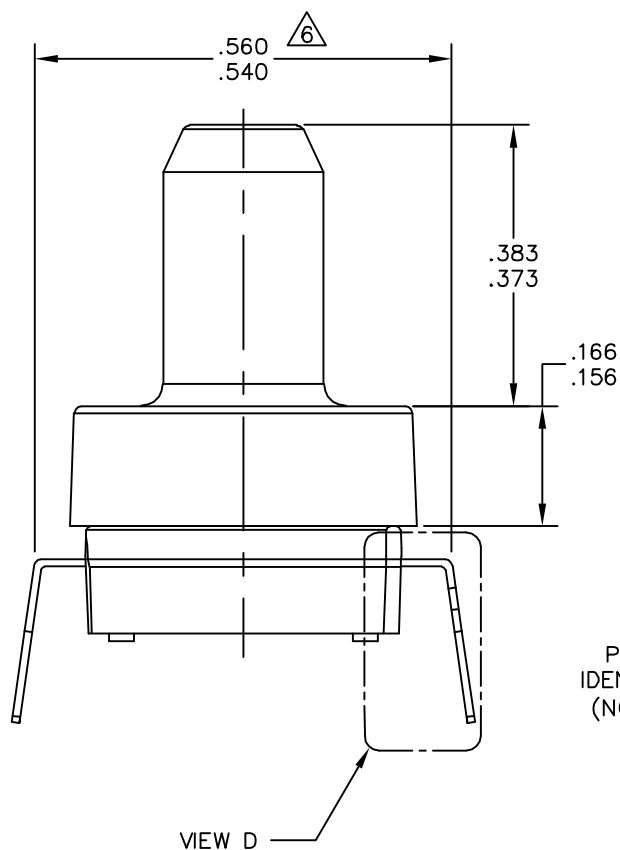
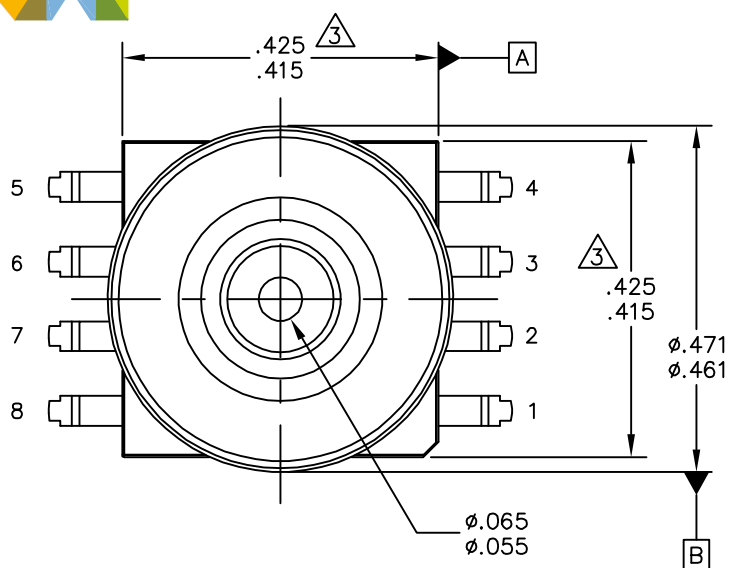
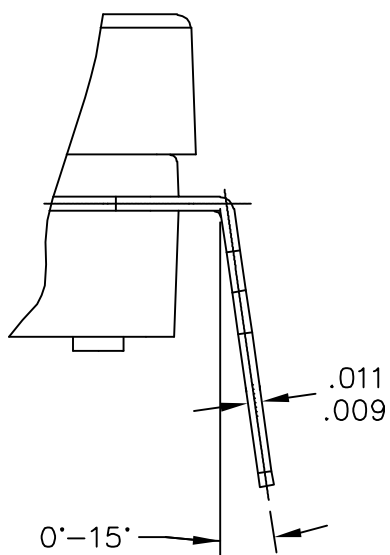




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TITLE: SO, 8 I/O, .420 X .420 PKG, .100 IN PITCH	DOCUMENT NO: 98ASA00255D REV: B	
	STANDARD: NON-JEDEC	
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VIEW D

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		STANDARD: NON-JEDEC	
		SOT1678-1	07 JAN 2016



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M – 1994.

2. CONTROLLING DIMENSION: INCH.

3. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION.

4. MAXIMUM MOLD PROTRUSION IS .006.

5. ALL VERTICAL SURFACES 5° TYPICAL DRAFT.

6. DIMENSION TO CENTER OF LEAD WHEN FORMED PARALLEL.

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